

# MA3G655 (MA655)

Silicon planar type (cathode common)

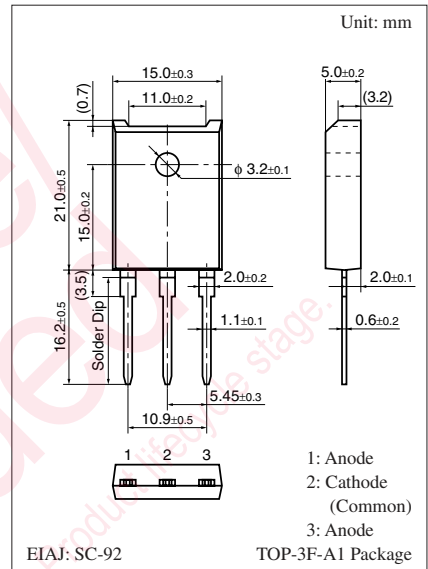
For high-frequency rectification

**■ Features**

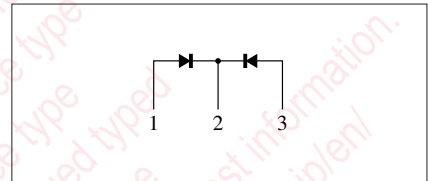
- High reverse voltage  $V_R$
- Low forward voltage  $V_F$
- Fast reverse recovery time  $t_{rr}$

**■ Absolute Maximum Ratings**  $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Repetitive peak reverse voltage	$V_{RRM}$	300	V
Non-repetitive peak reverse surge voltage	$V_{RSM}$	300	V
Forward current (Average)	$I_{F(AV)}$	20	A
Non-repetitive peak forward surge current	$I_{FSM}$	150	A
Junction temperature	$T_j$	-40 to +150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-40 to +150	$^\circ\text{C}$



**Internal Connection**



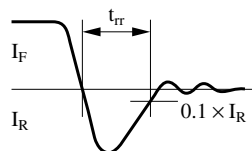
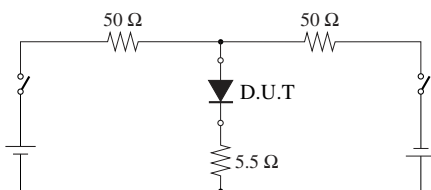
**■ Electrical Characteristics**  $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 10\text{ A}, T_C = 25^\circ\text{C}$			1.0	V
Repetitive peak reverse current	$I_{RRM1}$	$V_{RRM} = 300\text{ V}, T_C = 25^\circ\text{C}$			20	$\mu\text{A}$
		$V_{RRM} = 300\text{ V}, T_j = 150^\circ\text{C}$			5	mA
Reverse recovery time *	$t_{rr}$	$I_F = 1\text{ A}, I_R = 1\text{ A}$			50	ns
Thermal resistance (j-c)	$R_{th(j-c)}$				1.5	$^\circ\text{C/W}$
Thermal resistance (j-a)	$R_{th(j-a)}$				40	$^\circ\text{C/W}$

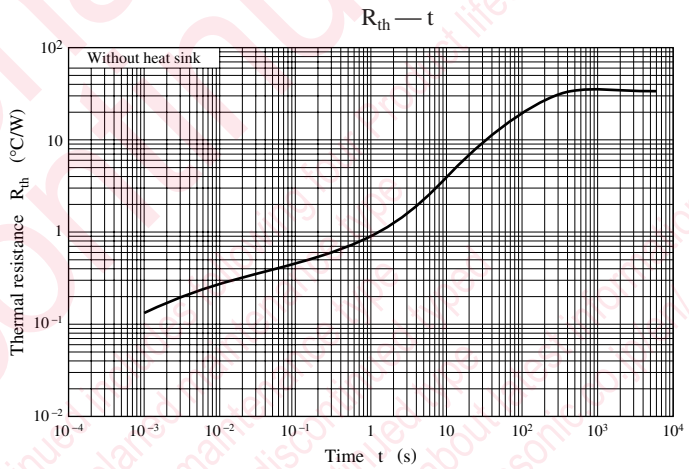
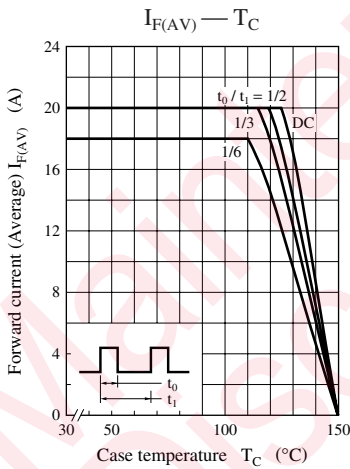
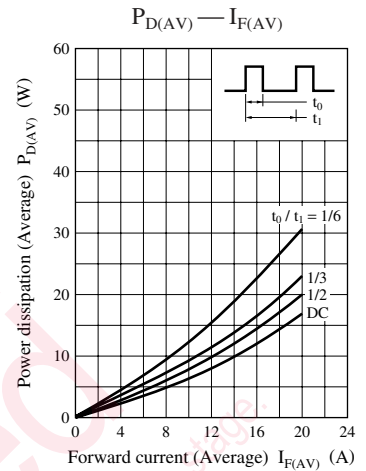
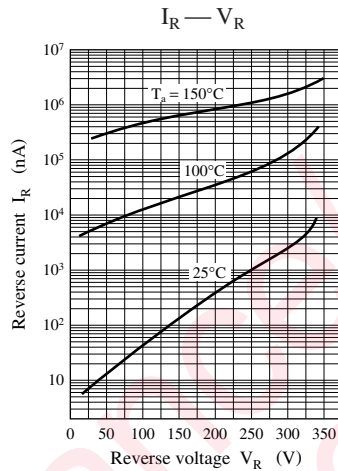
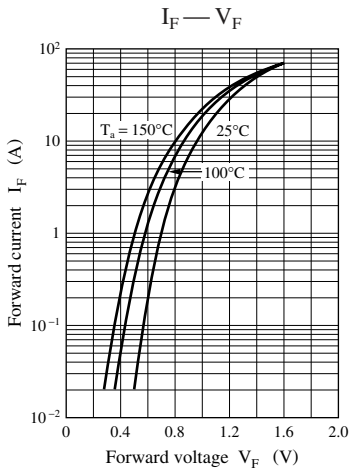
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 10 MHz.

3. \*:  $t_{rr}$  measurement circuit



Note) The part number in the parenthesis shows conventional part number.



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